

L Number	Hits	Search Text	DB	Time stamp
262	14	"5945736"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 13:15
263	37	"5397919"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 13:17
264	11	"5579827"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 13:17
265	47	"5313099"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 13:18
266	46	"5329426"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 13:22
267	4	"6166435"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 13:23
268	114	"5945736" "5397919" "5579827" "5313099" "5329426" "6166435"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 13:23
269	23	("2432513"   "2916159"   "2958515"   "3033537"   "3146384"   "3182114"   "3229756"   "3417300"   "4481525"   "4576224"   "4607685"   "4745456"   "4753287"   "4924352"   "5170323"   "5313099"   "5945736"   "6014315"   "6021045"   "6075699"   "6093961"   "6116120"   "6236569").PN.	USPAT	2003/01/25 13:26
282	2	6166435.URPN.	USPAT	2003/01/25 13:29
283	3	("5153379"   "5917702"   "5977626").PN.	USPAT	2003/01/25 13:29
284	3	5885848.URPN.	USPAT	2003/01/25 13:32
285	19	("4612978"   "4748495"   "4884169"   "5227663"   "5285352"   "5293930"   "5311060"   "5355283"   "5386342"   "5397919"   "5451274"   "5467253"   "5525835"   "5528159"   "5555488"   "5610442"   "5619070"   "5620928"   "5672547").PN.	USPAT	2003/01/25 13:32
286	23578	semiconductor near1 (housing package)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 13:59
287	24642	(cap lid (heat adj sink)) near3 (rotated rotating slided sliding slide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 14:02
288	40	(semiconductor near1 (housing package)) and ((cap lid (heat adj sink)) near3 (rotated rotating slided sliding slide))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 14:02
289	10	5571027.URPN.	USPAT	2003/01/25 14:08
290	6	("4684184"   "4832612"   "4846703"   "5127837"   "5180976"   "5397245").PN.	USPAT	2003/01/25 14:10
291	32	4832612.URPN.	USPAT	2003/01/25 14:13
292	0	6338409.URPN.	USPAT	2003/01/25 14:15
293	8	("4706161"   "4757355"   "4832612"   "5314068"   "5482161"   "5713711"   "5740845"   "5896729").PN.	USPAT	2003/01/25 14:16
294	2	5938454.URPN.	USPAT	2003/01/25 14:18

295	11	("4063791"   "4597617"   "4832612"   "5059129"   "5068601"   "5137461"   "5185073"   "5321583"   "5468158"   "5691041"   "5793618").PN.	USPAT	2003/01/25 14:19
296	7	5919050.URPN.	USPAT	2003/01/25 14:21
297	13	("Re30604"   "4007479"   "4351580"   "4354720"   "4390220"   "4513353"   "4535887"   "4547794"   "4564880"   "4575747"   "4597617"   "4696526"   "4725922").PN.	USPAT USPAT	2003/01/25 14:22
298	6	("4684184"   "4832612"   "4846703"   "5127837"   "5180976"   "5397245").PN.	USPAT	2003/01/25 14:23

L Number	Hits	Search Text	DB	Time stamp
317	1388	257/704	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 14:53
318	11920	(cap lid (heat adj sink)) near2 (rotated rotating)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:18
319	2	257/704 and ((cap lid (heat adj sink)) near2 (rotated rotating))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 14:58
320	0	6020632.URPN.	USPAT	2003/01/25 14:57
321	10	("3855606"   "4054814"   "4281993"   "4878107"   "5068866"   "5296724"   "5340993"   "5808325"   "5825054"   "5878069").PN.	USPAT	2003/01/25 14:57
322	880	((cap lid (heat adj sink)) near2 (rotated rotating)) and (chip semiconductor die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:02
323	164359	(base substrate) near3 (housing cavity opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:01
324	187	((cap lid (heat adj sink)) near2 (rotated rotating)) and (chip semiconductor die)) and ((base substrate) near3 (housing cavity opening))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:01
325	10946	((base substrate) near3 (housing cavity opening)) with (chip semiconductor die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:02
326	30	((cap lid (heat adj sink)) near2 (rotated rotating)) and ((base substrate) near3 (housing cavity opening)) with (chip semiconductor die))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:20
327	2	6049215.URPN.	USPAT	2003/01/25 15:06
328	29	("3766439"   "4169642"   "4341842"   "4386815"   "4427249"   "4567432"   "4597617"   "4679118"   "4684184"   "4750890"   "4789345"   "4812191"   "4832612"   "4846703"   "4846704"   "4859189"   "4883428"   "4922376"   "5006792"   "5066357"   "5073117"   "5123850"   "5127837"   "5180976"   "5225037"   "5302891"   "5397245"   "5402077"   "5468157").PN.	USPAT	2003/01/25 15:07
329	31	5402077.URPN.	USPAT	2003/01/25 15:08
330	1	5132535.URPN.	USPAT	2003/01/25 15:17
331	6	("3655975"   "3665194"   "4518860"   "4704537"   "4920272"   "4992658").PN.	USPAT	2003/01/25 15:17
332	13050	(cap lid (heat adj sink)) near2 (rotated rotating twisting twisted)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:19
333	1130	((cap lid (heat adj sink)) near2 (rotated rotating twisting twisted)) not ((cap lid (heat adj sink)) near2 (rotated rotating))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:20
334	1	((cap lid (heat adj sink)) near2 (rotated rotating twisting twisted)) not ((cap lid (heat adj sink)) near2 (rotated rotating)) and ((base substrate) near3 (housing cavity opening)) with (chip semiconductor die))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:20
335	31	((cap lid (heat adj sink)) near2 (rotated rotating twisting twisted)) and ((base substrate) near3 (housing cavity opening)) with (chip semiconductor die))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/25 15:20